



## Silicon Carbide Power MOSFET 650V N-Channel MOS

### ■ Applications

- Switch Mode Power Supplies
- High Voltage DC/DC Converters
- Battery Chargers
- Motor Drives
- Pulsed Power applications

### ■ Features

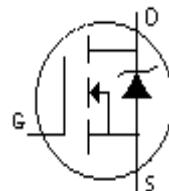
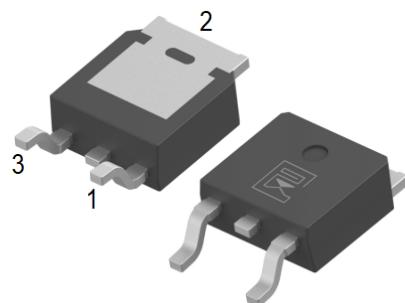
- High Blocking Voltage with Low On-Resistance
- High Speed Switching with Low Capacitances
- Easy to Parallel and Simple to Drive
- Avalanche Ruggedness
- Halogen Free, RoHS Compliant

### ■ Product Summary

V <sub>DS</sub>	650	V
I <sub>D</sub>	19	A
R <sub>DS(ON)</sub> , Typ@18V	140	mΩ
Q <sub>g</sub>	29	nC

### ■ Benefits

- Higher System Efficiency
- Reduced Cooling Requirements
- Increased Power Density
- Increased System Switching Frequency



Gate: 1  
Drain: 2  
Source: 3

TO-252

Marking	Package	Packaging	Min. package quantity
MK3C180R065	TO-252	Tape & Reel	3000



**■ Absolute Maximum Ratings (Tc=25°C unless otherwise noted)**

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V <sub>DS</sub>	650	V
Gate-Source Voltage	V <sub>GS</sub>	- 10/+22	V
Recommended operational values	V <sub>GSO<sub>p</sub></sub>	0/+18	V
Continuous Drain Current Tc=25°C V <sub>GS</sub> =18V (Note 1)	I <sub>D</sub>	19	A
Continuous Drain Current Tc=100°C V <sub>GS</sub> =18V (Note 1)		13	A
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	38	A
Total Dissipation	P <sub>D</sub>	75	W
Junction Temperature	T <sub>j</sub>	175	°C
Storage Temperature	T <sub>stg</sub>	- 55~175	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

**■ Thermal Characteristics**

Parameter	Symbol	Max	Unit
Maximum Junction-to-Case	R <sub>θJC</sub>	2	°C/W
Maximum Junction-to-Ambient	R <sub>θJA</sub>	60	°C/W

Note 1: Ensure that the channel temperature does not exceed 175°C.

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.





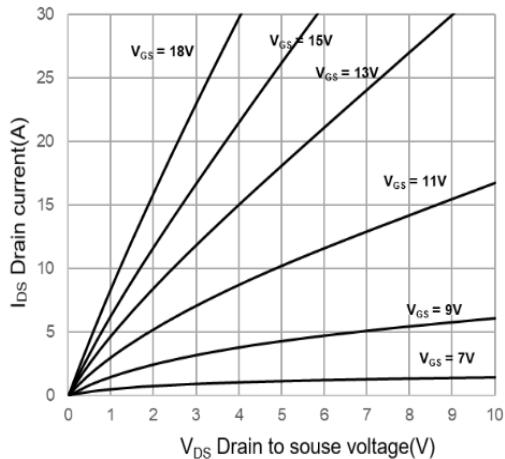
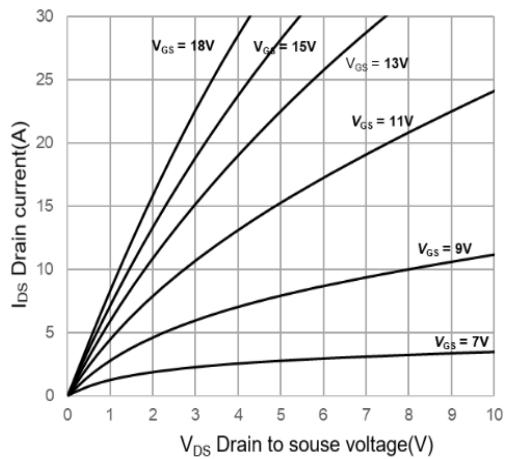
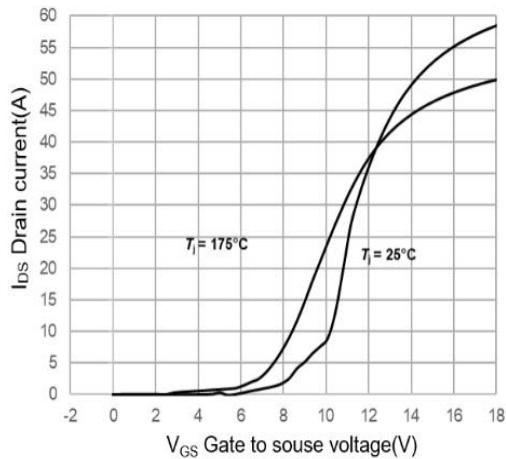
## ■ Electrical Characteristics (Tc=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =500uA	650	-	-	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =650V, V <sub>GS</sub> =0V	-	-	1	uA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =18V, V <sub>DS</sub> =0V	-	-	100	nA
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> =5mA	3.0	3.8	5.0	V
Drain-Source On Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =15V, I <sub>D</sub> =10A	-	200	240	mR
		T <sub>j</sub> =175°C	-	180	-	
		V <sub>GS</sub> =18V, I <sub>D</sub> =10A	-	140	180	
		T <sub>j</sub> =175°C	-	160	-	
Transconductance	g <sub>fs</sub>	V <sub>GS</sub> =20V, I <sub>D</sub> =10A	-	1.7	-	s
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHz	-	503	-	pF
Output Capacitance	C <sub>oss</sub>		-	141	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	10	-	pF
Gate Resistance	R <sub>g</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1.0MHz	-	2.9	-	Ω
<b>Switching Parameters</b>						
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =500V, V <sub>GS</sub> =0/15 V I <sub>D</sub> = 8.5A, R <sub>G(ext)</sub> =10Ω	-	15	-	ns
Turn-On Rise Time	t <sub>r</sub>		-	55	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>		-	32	-	ns
Turn-Off Fall Time	t <sub>f</sub>		-	70	-	ns
Turn-On Switching Energy	E <sub>ON</sub>		-	57	-	uJ
Turn-Off Switching Energy	E <sub>OFF</sub>		-	7.3	-	uJ
Total Gate Charge	Q <sub>g</sub>	V <sub>DD</sub> =500V, V <sub>GS</sub> =0/15 V I <sub>D</sub> = 8.5A	-	29	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	8.2	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	14.1	-	nC
<b>Source-Drain Characteristics</b>						
Diode Forward Voltage	V <sub>sd</sub>	V <sub>GS</sub> =0V, I <sub>SD</sub> = 5 A,	-	3.4	-	V
Continuous Diode Forward Current	I <sub>S</sub>	T <sub>c</sub> =25°C	-	19	-	A
Reverse Recovery Time	t <sub>rr</sub>	V <sub>R</sub> =400V, I <sub>F</sub> =20A, di/dt=100A/us	-	26	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		-	19.5	-	nC
Peak Reverse Recovery Current	I <sub>mm</sub>		-	1.5	-	A

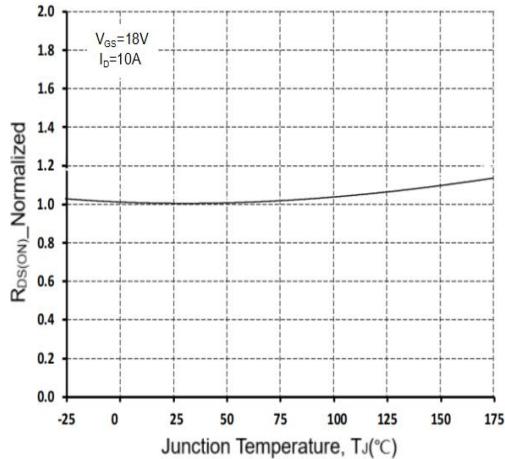




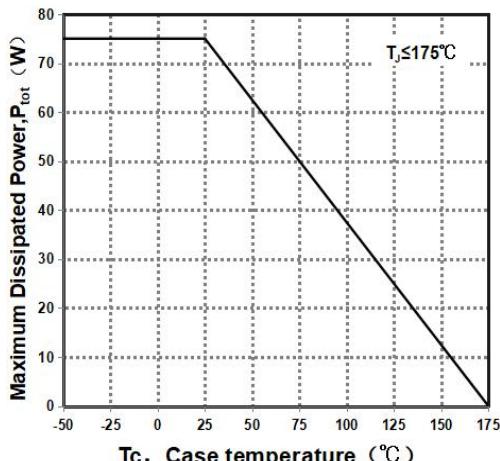
## ■ Characteristics Curves

Output Characteristics  $T_J=25^\circ\text{C}$ Output Characteristics  $T_J=175^\circ\text{C}$ 

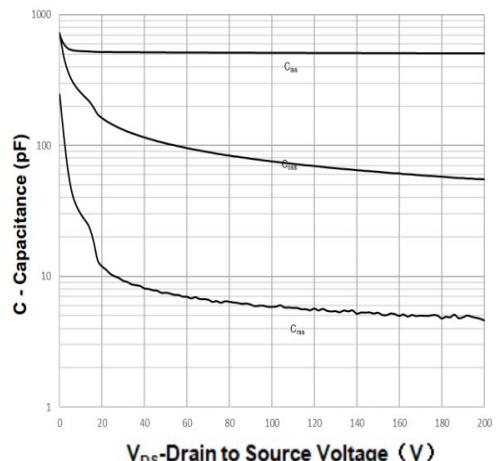
Transfer Characteristics



Normalized On-Resistance vs. Temperature

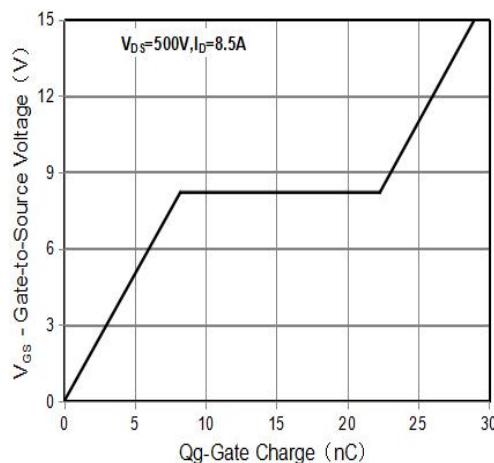


Power Dissipation Derating

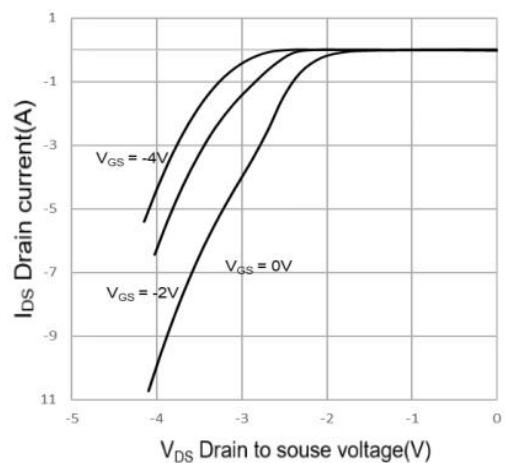
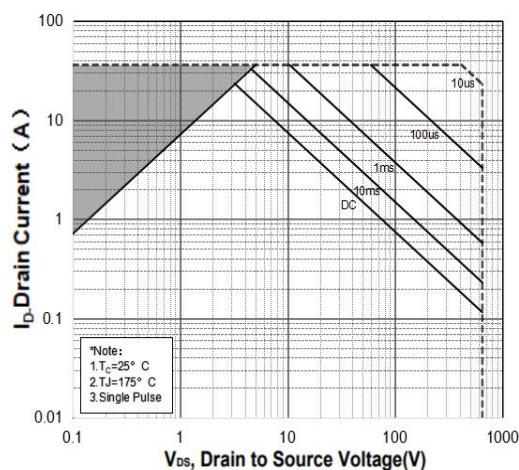


Capacitance





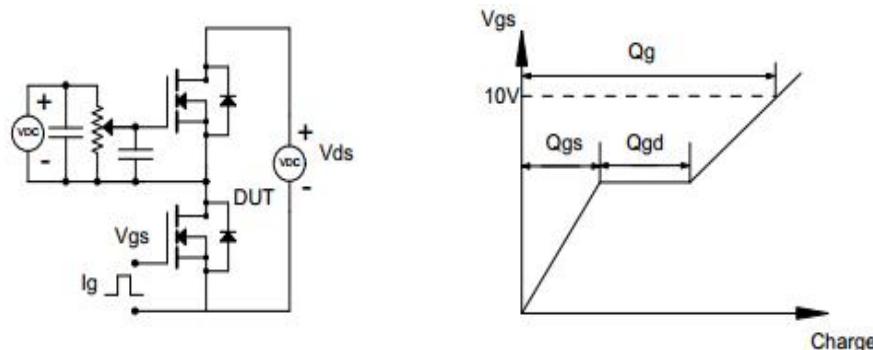
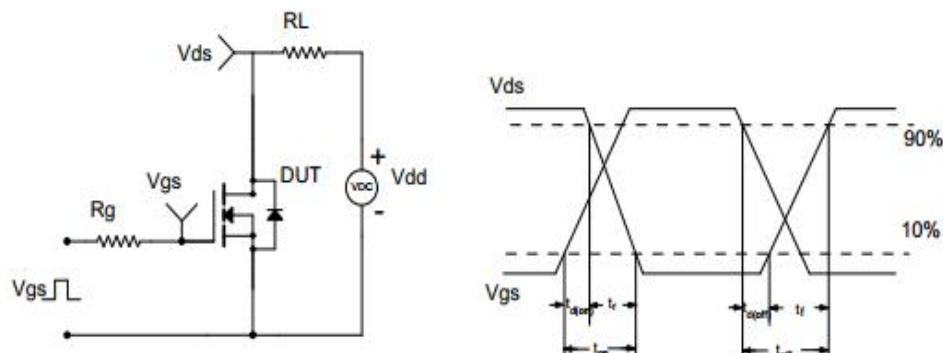
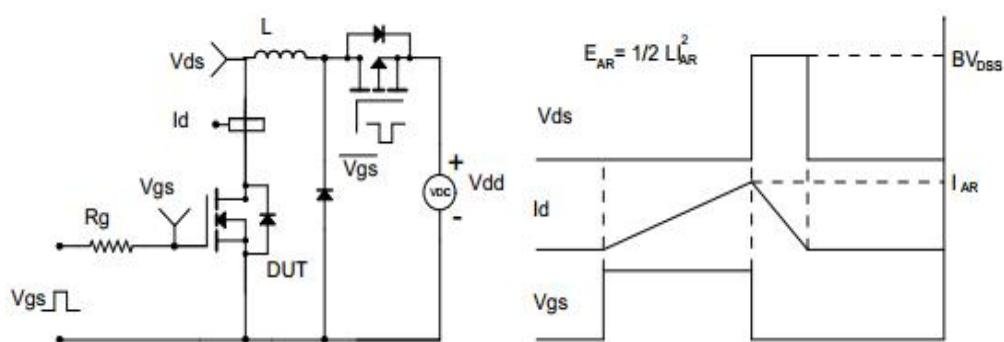
Gate Charge Waveform

Source-Drain Diode Characteristics,  $T_J=25^\circ C$ 

Safe Operating Area

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



**■ Test Circuit & Waveform****Gate Charge Test Circuit & Waveform****Resistive Switching Test Circuit & Waveform****Unclamped Inductive Switching (UIS) Test Circuit & Waveform**



## ■ TO-252 Package Dimensions

Unit: mm

Symbol	Min	Nom	Max	Symbol	Min	Nom	Max
A	2.10		2.50	E	5.80		6.30
B	0.80		1.25	e1	2.25	2.30	2.35
b	0.50		0.85	e2	4.45		4.75
b1	0.50		0.90	L1	9.50		10.20
b2	0.45		0.60	L2	0.90		1.45
C	0.45		0.60	L3	0.60		1.10
D	6.35		6.75	K	-0.1		0.10
D1	5.10		5.50				

